LNJ912W8CRA1

Hight Bright Surface Mounting Chip LED

TSS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	65	mW	
Forward current	I_{F}	15	mA	
Pulse forward current *	I_{FP}	55	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Lighting Color

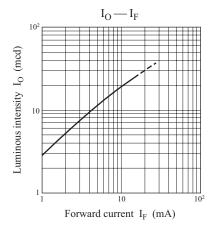
• Blue

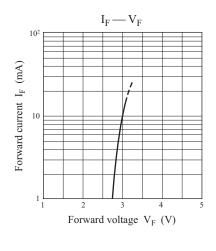
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

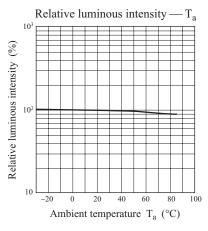
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

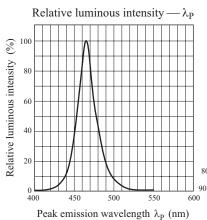
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	5.0	12.0	41.8	mcd
Reverse current	I_R	$V_R = 5 V$			100	μΑ
Forward voltage	V _F	$I_F = 5 \text{ mA}$		2.90	3.20	V
Peak emission wavelength	λ_{P}	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 5 \text{ mA}$	462	470	478	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		20		nm

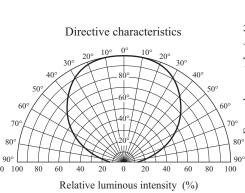
Note) *1: Measurement tolerance: ±20% *2: Measurement tolerance: ±3 nm

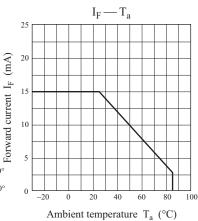




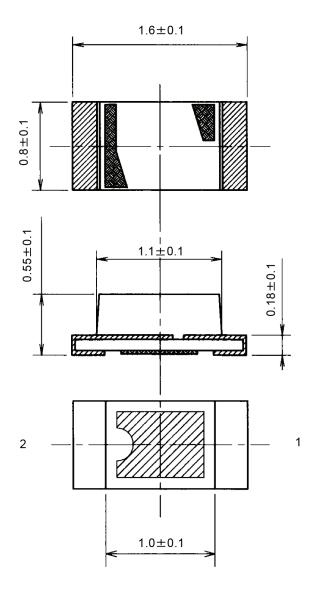




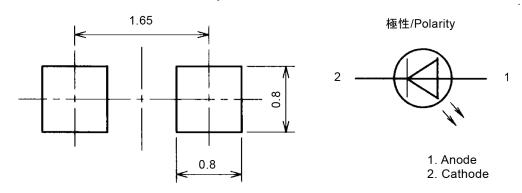




■ Package (Unit: mm)



推奨パターン/Recommended Land Layout



(注 1) パッケージ寸法については電極バリを含まない。 (Note1) Electrode projection is not included in the package dimensions.

2 Ver. DEK

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